

## **Description**

The AP3N9R5AMT uses advanced trench technology to provide excellent  $R_{DS(ON)}$ , low gate charge and operation with gate voltages as low as 4.5V. This device is suitable for use as a Battery protection or in other Switching application.

## DFN5X6-8L

## **General Features**

 $V_{DS} = 30V I_{D} = 50A$ 

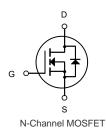
 $R_{DS(ON)} < 8.5 m\Omega V_{GS} = 10V$ 

## **Application**

Battery protection

Load switch

Uninterruptible power supply



**Package Marking and Ordering Information** 

Product ID	Pack	Brand	Qty(PCS)
AP3N9R5AMT	DFN5X6-8L	HXY MOSFET	5000

Absolute Maximum Ratings (Tc=25°C unless otherwise noted)

Symbol	Parameter	Rating	Units		
VDS	Drain-Source Voltage	30	V		
Vgs	Gate-Source Voltage	V			
I <sub>D</sub> @T <sub>C</sub> =25°C	Continuous Drain Current, V <sub>GS</sub> @ 10V	Continuous Drain Current, V <sub>GS</sub> @ 10V 60			
Ib@Tc=100°C	Continuous Drain Current, V <sub>GS</sub> @ 10V	38	Α		
Ірм	Pulsed Drain Current <sup>1</sup>	А			
EAS	Single Pulse Avalanche Energy <sup>2</sup> 36		mJ		
las	Avalanche Current	50	Α		
P <sub>D</sub> @T <sub>C</sub> =25°C	Total Power Dissipation <sup>4</sup>	31	W		
Тѕтс	Storage Temperature Range	-55 to 150	°C		
TJ	Operating Junction Temperature Range	Operating Junction Temperature Range -55 to 150			
Reja	Thermal Resistance Junction-Ambient	62	°C/W		
Rejc	Thermal Resistance Junction-Case <sup>3</sup>	27	°C/W		



## Electrical Characteristics (T<sub>J</sub>=25°C unless otherwise noted)

Symbol	Parameter	Conditions	Min	Тур	Max	Units
BV <sub>DSS</sub>	Drain-Sourtce Breakdown Voltage	V <sub>GS</sub> =0V,I <sub>D</sub> =250μA	30			V
I <sub>DSS</sub>	Zero Gate Voltage Drain Current	V <sub>GS</sub> =0V, V <sub>DS</sub> =24V			1	μΑ
I <sub>GSS</sub>	Gate-Source Leakage Current	V <sub>GS</sub> =±20V, V <sub>DS</sub> =0A			±100	nA
V <sub>GS(th)</sub>	GATE-Source Threshold Voltage	V <sub>GS</sub> =V <sub>DS</sub> , I <sub>D</sub> =250μA	1.2	1.5	2.5	V
R	Drain-Source On Resistance <sup>4</sup>	V <sub>GS</sub> =10V,I <sub>D</sub> =30A 6		6.5	8.5	
R <sub>DS(ON)</sub>		V <sub>GS</sub> =4.5V,I <sub>D</sub> =15A		11	14	mΩ
G <sub>FS</sub>	Forward Transconductance	V <sub>DS</sub> =5V, I <sub>D</sub> =30A		38		S
C <sub>iss</sub>	Input Capacitance			1317	1844	pF
C <sub>oss</sub>	Output Ca pacitance	$V_{DS} = 15V, V_{GS} = 0V,$ f=1MHz		163	228	
C <sub>rss</sub>	Reverse Transfer Capacitance	1-111112		131	183	
t <sub>d(on)</sub>	Turn-On Delay Time			4.6	9.2	ns
t <sub>r</sub>	RiseTime	V <sub>DD</sub> =15V,I <sub>D</sub> =15A,		12.2	22	ns
$t_{d(off)}$	Turn-Off Delay Time	$V_{GS}$ =15 $V$ , $R_{G}$ =3.3 $\Omega$		26.6	53	ns
t <sub>f</sub>	Fall Time			8	16	ns
$Q_g$	Total Gate Charge			17.6	21	nC
$Q_{gs}$	Gate-Source Charge	V <sub>GS</sub> =4.5V,		2:35	5.9	nC
$Q_{gd}$	Gate-Drain "Miller" Charge	V <sub>DS</sub> =15V, I <sub>D</sub> =15A		5.9	7.1	nC
$V_{SD}$	Source-Drain Diode Forward Voltage	V <sub>GS</sub> =0V,I <sub>S</sub> =1A			1	٧
IS	Continuous Source Current	VG=VD=0V,			58	Α
ISM	Pulsed Source Current	Force Current			115	А
trr	Reverse Recovery Time	IF=30A ,		9.2		ns
Qrr	Reverse Recovery Charge	dI/dt=100A/¦ÌsTJ=25℃		2		nC

#### Notes:

- 1. Repetitive Rating: Pulse Width Limited by Maximum Junction Temperature.
- 2.  $E_{AS}$  condition: Starting  $T_J$ =25C,  $V_{DD}$ =15V,  $V_G$ =10V,  $R_G$ =25ohm, L=0.5mH,  $I_{AS}$ =14A
- 3. R<sub>0,JA</sub> is measured with the device mounted on a 1inch<sup>2</sup> pad of 2oz copper FR4 PCB
- 4. Pulse Test: Pulse Width≤300µs, Duty Cycle≤0.5%.



## **Typical Characteristics**

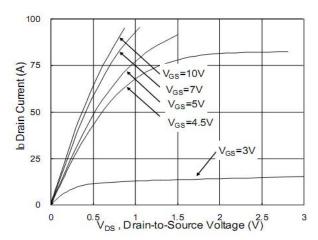


Fig.1 Typical Output Characteristics

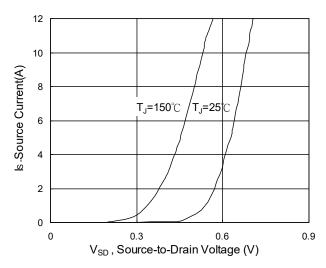


Fig.3 Forward Characteristics of reverse

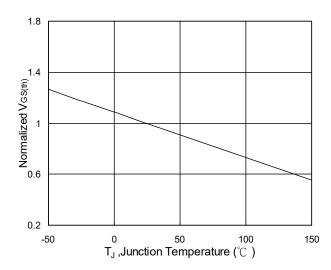


Fig.5 Normalized  $V_{GS(th)}$  vs.  $T_J$ 

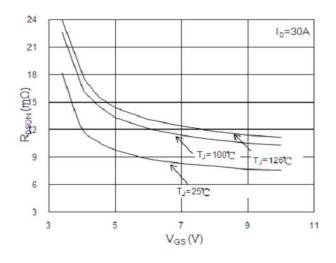


Fig.2 On-Resistance vs. Gate-Source

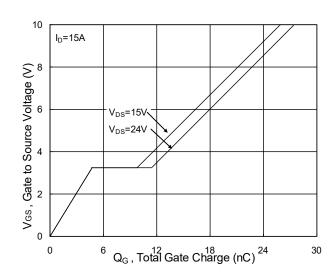


Fig.4 Gate-Charge Characteristics

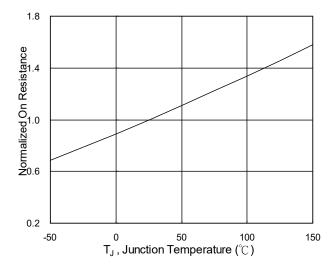
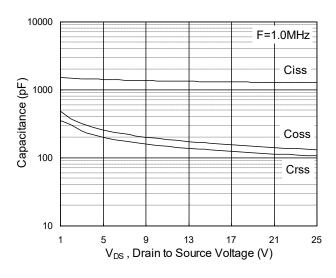


Fig.6 Normalized R<sub>DSON</sub> vs. T<sub>J</sub>





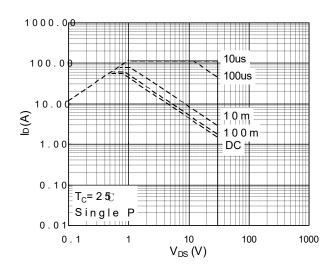
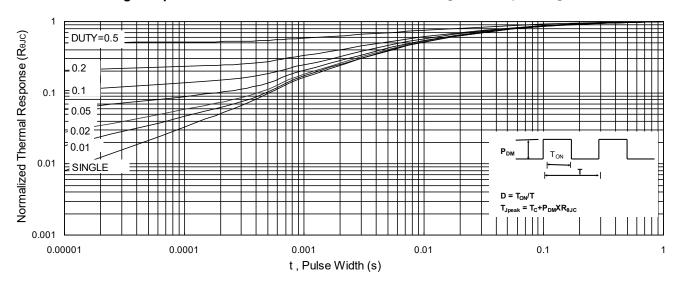
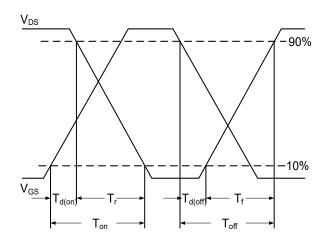


Fig.7 Capacitance

Fig.8 Safe Operating Area





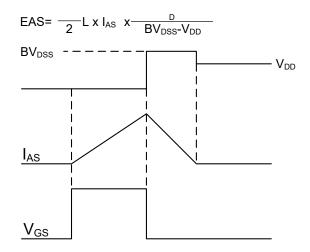
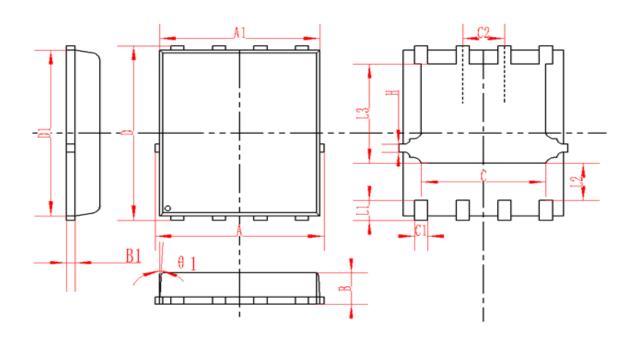


Fig.10 Switching Time Waveform



# **DFN5X6-8L Package Information**



SYMBOL	MM		INCH			
	MIN	NOM	MAX	MIN	NOM	MAX
Α	5.3	5.5	5.7	0.208	0.216	0.224
A1	5.1	5.2	5.3	0.2	0.204	0.209
D	5.98	6	6.02	0.235	0.236	0.237
D1	5.85	6.05	6.25	0.23	0.238	0.246
В	0.85	0.95	1.05	0.033	0.037	0.041
B1	0.254REF		0.010REF			
С	3.95	4	4.05	0.156	0.157	0.159
C1	0.35	0.4	0.45	0.014	0.016	0.018
C2		1.27TYP			0.5TYP	
θ1	8°	10°	12°	8°	10°	12°
L1	0.63	0.64	0.65	0.025	0.025	0.026
L2	1.2	1.3	1.4	0.047	0.051	0.055
L3	3.415	3.42	3.425	0.134	0.135	0.135
Н	0.24	0.25	0.26	0.009	0.010	0.010



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